

# **Description**

The GL7101 is high power LED driver with 350mA constant rated source current. It features low dropout voltage and low quiescent current, marking it ideal for battery powered application.

The GL7101 is available in the 5-lead SOT-23-5 package.

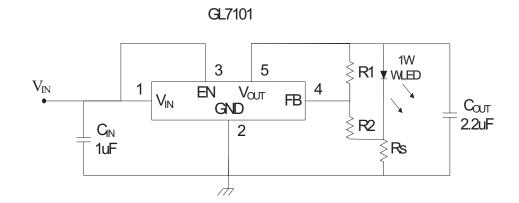
## **Application**

**Power LED Driver** 

## **TYPICAL APPLICATIONS**

#### **Features**

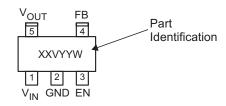
- High Efficiency 92%
- Up to 350mA Constant Source Current
- Low Quiescent Current: Typ. 65uA
- 0.5uA Shutdown Current
- **Short Circuit Protection**
- **Open Load LED Protection**
- **Over Temperature Protection**
- Space Saving Package SOT-23-5





## **MARKING INFORMATION & PIN CONFIGURATIONS**

## SOT-25 (SOT-23-5)



XX = Marking Code(**AA** = GL7101)

V = Voltage Code YY = Year

= Weekly

## ORDERING INFORMATION (Green Package Products are available now!)

Ordering Number	Output Voltage	Package	Shipping
GL7101-ST25R	N/A	SOT-23-5	3000 Units / Reel

For detail Ordering Number identification, please see last page.

### **ABSOLUTE MAXIMUM RATINGS**

Rating	Value	Unit
Input Voltage	6.0	V
Output Current	350	mA
Output Voltage	GND-0.3 to VIN+0.3	V
Storage Temperature Range	-65 to +150	°C
Lead Temperature (Soldering, 5 sec.)	+300	°C
Thermal Resistance (Junction to Case)	+130	°C/W
Thermal Resistance (Junction to Ambient)	+250	°C/W
Internal Power Dissipation (P <sub>D</sub> )	400	mW

#### OPERATING CONDITIONS

Rating	Value	Unit
Ambient Temperature Range	- 40 ~ +85	°C
Junction Temperature Range	-40 ~ <b>+</b> 125	°C

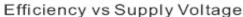


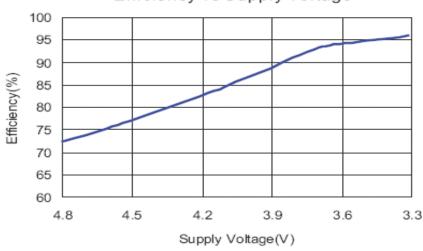
#### **ELECTRICAL CHARACTERISTICS:**

 $T_A = 25$ ,  $C_{IN} = 1$ uF,  $C_{OUT} = 2.2$ uF, Vin = 3.7V, unless otherwise noted.

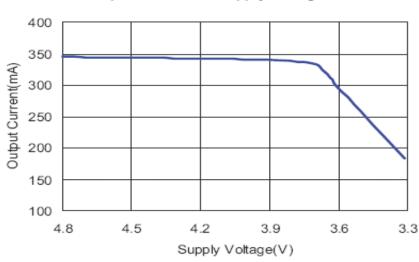
Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Input Voltage Range		V <sub>IN</sub>	-	-	5.5	V
Output Current		I <sub>out</sub>	300	-	-	mA
Quiescent Current	No Load	Ι <sub>Q</sub>	-	65	90	uA
Efficiency		η	-	90	92	%
Over Temperature Shutdown	I <sub>ουτ</sub> =1mA	OTS	-	150	-	°C
Over Temperature Hysteresis	I <sub>out</sub> =1mA	ОТН	-	30	-	°C

 $\begin{array}{l} \textbf{Typical Performance Characteristics} \\ \textbf{T}_{A} = 25 ^{\circ} \textbf{C}, \textbf{C}_{IN} = 1 \text{uF}, \textbf{C}_{OUT} = 2.2 \text{uF}, \textbf{R}1 = 62 \text{K}\Omega, \textbf{R}2 = 33 \text{K}\Omega, \textbf{R}_{S} = 0.22 \Omega. \end{array}$ 





### Output Current vs Supply Voltage





# **Application Information**

In the typical application (see Figure 1), the LED current will come to the constant current level little by little after the device is powered. A  $62 \text{K}\Omega$  resistor is recommended to be chosen for R1, the value chosen for R2 should be adjusted small around  $33 \text{K}\Omega$  due to the disuniform LED forward voltage resulted from LED lot-to-lot or brand-to-brand variations.

#### **Power Dissipation and Thermal Consideration**

Thermal protection limits power dissipation in the GL7101. When the operation junction temperature exceeds 150 C, the OTP (Over Temperature Protection) starts the thermal shutdown and turns the pass transistor off. The pass transistor resumes operation after the junction temperature drops below 120 C.

For continuous operation, the junction temperature should be maintained below 125 C. The power dissipation is defined as:

$$\mathsf{P}_{\scriptscriptstyle \mathsf{D}} = (\mathsf{V}_{\scriptscriptstyle \mathsf{IN}} - \mathsf{V}_{\scriptscriptstyle \mathsf{OUT}})^* \mathsf{I}_{\scriptscriptstyle \mathsf{OUT}} + \mathsf{V}_{\scriptscriptstyle \mathsf{IN}}^* \mathsf{I}_{\scriptscriptstyle \mathsf{GND}}$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surrounding airflow and temperature difference between junction and ambient. The maximum power dissipation can be calculated by the following formula:

$$P_{\text{D(MAX)}} \ = \ \frac{T_{\text{J(MAX)}} \text{-} T_{\text{A}}}{\theta_{\text{JA}}}$$

Where  $T_{J_{(MAX)}}$  is the maximum operation junction temperature 125 C.T<sub>A</sub> is the ambient temperature.  $\theta_{JA}$  is the thermal resistance from the junction to the ambient.

For example,  $\theta_{\rm JA}$  is 250 C/W for SOT-23, based on the standard JEDEC 51-3 for a single-layer thermal test board. The maximum power dissipation at T $_{\rm A}$ =25 C can be calculated by following formula:

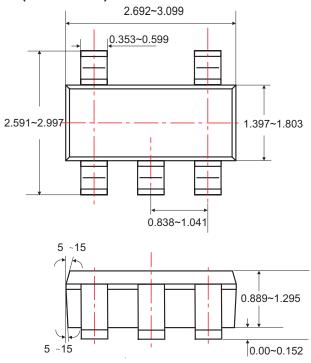
 $P_{D_{(MAX)}} = (125 \text{ C}-25 \text{ C})/250=0.4 \text{W} \text{ for SOT-23}$  package

For example, how to calculate the junction temperature of the GL7101 SOT-23 package? If we use input voltage  $V_{\rm IN}$ =4V, at an output current  $I_{\rm o}$ =300mA and the case temperature  $T_{\rm a}$ =40 C measured by the thermal couple while operating, then our power dissipation is defined as:

 $P_D = (4V-2.8V)*300mA+4V*70uA \approx 360mW$ 



## ◆ SOT-25(SOT-23-5) PACKAGE OUTLINE DIMENSIONS



Unit: mm

## ORDERING NUMBER

